# PRODUCT SPOTLIGHT

## TB2249K

**Low Temperature Cure Structural Bonding Epoxy** 



### PRODUCT DESCRIPTION

**TB2249K** is a new low temperature cure structural one-part epoxy for bonding dissimilar materials. This heat-curing epoxy resin has a well-balanced shear bond strength and peel strength.

#### **APPLICATIONS**

Structural bonding of metal

Vertical and horizontal application - Thixotropic Index -1.9

Bonding primary structures in "Body in White" and Chassis

Weld bonding

Bonding of various metals - Fe, Al, SUS, Cu, GFRP

### **FEATURES**

High Strength - Lap Shear Strength > 30 MPa, T-Peel > 5 kN/m (Fe/Fel and AL/AL)

High Heat - 150°C (2000 hrs) no change

Moisture and Thermal Cycle Resistance - 40 to 150°C (2000 hrs) - little or no change

"Oily Surface" Adhesion - even with 100% oil coverage

**Excellent Impact Resistance** - 2.5 J (ISO 11343)

**Low Temperature Cure** - 130°C x 30 min

Storage - can be stored at 40°C for 2 months



